HD Communications Corp.

HD34387 MEMS Band Pass Filter

Features:

- Pass Band : 2.6G~ 4.0 GHz
- Insertion Loss : 3.0dB
- Size : 7.67x11.0x0.5mm

Absolute Maximum Ratings

- Max. Input Power : +35dBm
- Storage Temperature : -55 ~ +85Deg.C
- Operating Temperature : -55 ~ +125Deg.C

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Electrical Specifications (T_A=+25Deg.C, 50Ω system)

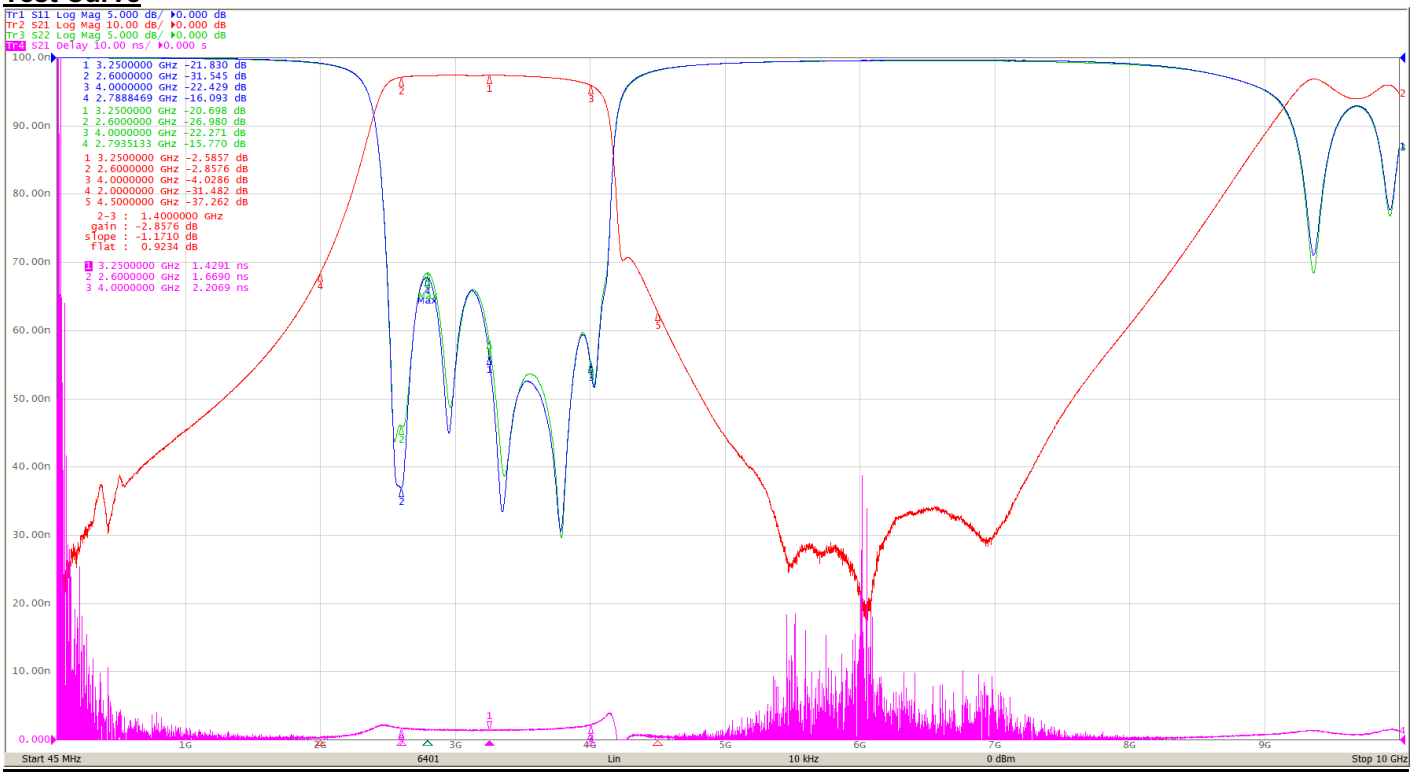
Parameter		Min.Value	Typical Value	Max.Value	Unit
Frequency Range		2.6 ~ 4.0			GHz
Insertion Loss (Fc)		-	2.58	3.0	dB
Ripple		-	0.92	1.3	dB
Attenuation	DC~@2GHz	30.0	31.48	-	dB
	@4.5GHz ~ 8GHz	30.0	37.26	-	dB
Return Loss		15.0	15.77	-	dB
Group Delay		-	2.20	4.0	ns

338 Jericho Tpke. Ste 387, Syosset, NY 11791
Tel: (631) 588-3877 Email: sales@hdcom.com

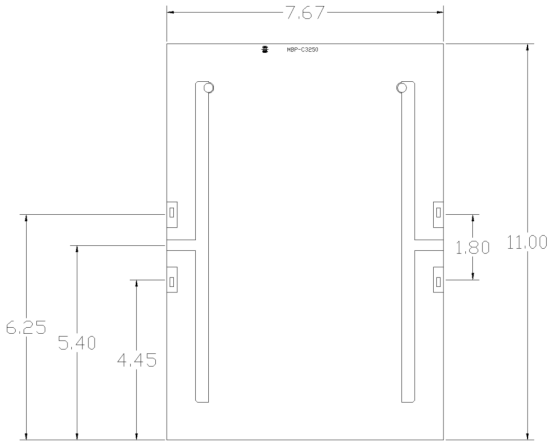
HD Communications Corp.

HD34387 MEMS Band Pass Filter

Test Curve



Size

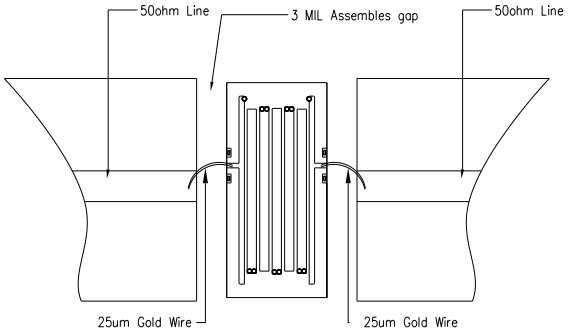


Remarks:Unit : mm, Tolerance : ±0.25mm
1. Chip bottom is gold plated and grounded.
2. Bonding pressure points are gold plated.
3. Don`t bond on the through holes.

338 Jericho Tpke. Ste 387, Syosset, NY 11791
Tel: (631) 588-3877 Email: sales@hdcom.com

Applications

1. Assembly and Bonding Diagram. (Reference)



Assembly Diagram

2. The chip is back-metalized and can be die mounted with AuSn eutectic performs or with electrically conductive epoxy (for example ME8456).
3. The die should be assembled on carriers like Kovar or Mu-Cu which have same Coefficient of thermal expansion. (2.9ppm/℃) with Silicon, thickness 0.2mm max.
4. Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.
5. Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers.

338 Jericho Tpke. Ste 387, Syosset, NY 11791
Tel: (631) 588-3877 Email: sales@hdcom.com